

WHAT IS CLAIMED IS:

1. A multilayer ceramic electronic part having an external electrode(s) formed from a thermosetting conductive paste comprising conductive particles having a high melting point, metal powder having a melting point of 300 °C or less and a resin(s).
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2. The multilayer ceramic electronic part according to claim 1, wherein the total content of said conductive particles having a high melting point and said metal powder having a melting point of 300 °C or less in said thermosetting conductive paste is in the range of 70 to 95% by weight relative to the total weight of said conductive particles having a high melting point, said metal powder having a melting point of 300 °C or less, and said resin(s).
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3. The multilayer ceramic electronic part according to claim 1 or 2, wherein a content of said metal powder having a melting point of 300 °C or less in said thermosetting conductive paste is in the range of 5 to 20% by weight relative to the total weight of said conductive particles having a high melting point and said metal powder having a melting point of 300 °C or less.
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4. A multilayer ceramic electronic part obtained according to a method comprising the steps of:
 - (1) providing a thermosetting conductive paste comprising conductive particles having a high melting point, metal powder having a melting point of 300 °C or less and a resin(s), and a ceramic composite body which is to be provided with an external electrode(s);
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 - (2) printing or applying said thermosetting conductive paste on or to a surface(s) where an internal electrode(s) of said ceramic composite body is led out; and
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 - (3) maintaining said ceramic composite body obtained in the step (2) at a temperature of 80 °C to 400 °C for a period of one to sixty minutes so as to form the external electrode(s).
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5. The multilayer ceramic electronic part according to

claim 4, wherein said conductive particle in said external electrode(s) makes a diffused junction with a metal of said internal electrode(s) of said multilayer ceramic composite body.

- 5 6. The multilayer ceramic electronic part according to any one of claims 1 to 5, wherein said multilayer ceramic electronic part is selected from the group consisting of a capacitor, a capacitor array, a thermistor, a varistor, an LC composite part, a CR composite part, an LR composite
10 part, and an LCR composite part.